

OCP – ODSA Project

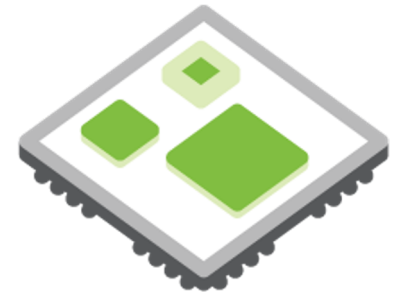
ODSA BoW256 PHY Development

NXP Semiconductors N.V

Gary Miller

Why ODSA at NXP Semiconductors

- 1. Motivation to use ODSA
 - a. NXP® is proceeding with ODSA BoW256 PHY design in one of our product technology nodes to validate and demonstrate readiness. The BoW256 PHY provides the opportunity for cost-efficient multi-chip products.
 - b. NXP has been involved in ODSA since 2018 in business and technical committees. Sam Fuller was involved in business committee leadership while Gayathri Bhagavatheeswaran, Alvin Loke, Thecla Chomicz, and Gary Miller are currently involved in technical working groups.



ODSA Use Case at NXP Semiconductors

- Product intersection with ODSA spec
 1. NXP has developed a number of multi-chip products and will continue with this accelerating industry trend. Intersection opportunities for BoW256 PHY are under consideration.
 2. BoW256 PHY and validation collateral are under development in 16-nm technology initially. The design is nearing completion with a target of 2Q22. Implementation will proceed afterwards.





Questions